



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC028N06LS3 G		<b>Issued</b>		19. July 2018	
<b>MA#</b>				MA001505924					
<b>Package</b>				PG-TDSON-8-39		<b>Weight*</b>		121.80 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.425	3.63	3.63	36333	36333	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		310		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	copper	7440-50-8	37.762	31.00	31.04	310029	310432	
wire	non noble metal	copper	7440-50-8	0.072	0.06	0.06	591	591	
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		652		
	plastics	epoxy resin	-	6.273	5.15		51503		
	inorganic material	silicondioxide	60676-86-0	33.351	27.38	32.60	273814	325969	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11918	11918	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1359	1359	
solder	noble metal	silver	7440-22-4	0.087	0.07		715		
	non noble metal	tin	7440-31-5	0.070	0.06		572		
	non noble metal	lead	7439-92-1	3.328	2.73	2.86	27326	28613	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.29	9.30	92939	93060	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	noble metal	silver	7440-22-4	1.032	0.85		8469		
	non noble metal	copper	7440-50-8	22.292	18.30	19.18	183018	191725	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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